



HSC2625

NPN EPITAXIAL PLANAR TRANSISTOR

Description

The HSC2625 is designed for triple diffused planer type high voltage, high speed switching applications.

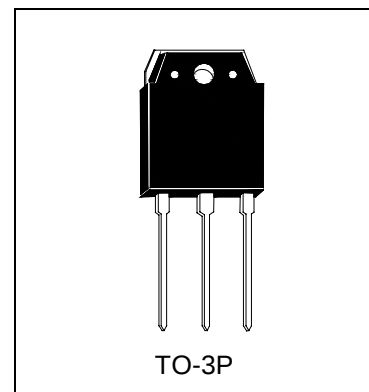
Absolute Maximum Ratings (Ta=25°C)

- Maximum Temperatures
Storage Temperature -55 ~ +150 °C
Junction Temperature..... +150 °C Maximum
- Maximum Power Dissipation
Total Power Dissipation (Tc=25°C) 80 W
- Maximum Voltages and Currents
VCBO Collector to Base Voltage 450 V
VCEO Collector to Emitter Voltage..... 400 V
VEBO Emitter to Base Voltage..... 7 V
IC Collector Current 10 A
IB Base Current..... 3 A

Characteristics (Ta=25°C)

Symbol	Min.	Typ.	Max.	Unit	Test Conditions
BVCBO	450	-	-	V	IC=1mA
BVCEO	400	-	-	V	IC=10mA
BVEBO	7	-	-		IE=100uA
ICBO	-	-	1	mA	VCB=450V
IEBO	-	-	100	uA	VEB=7V
*VCE(sat)	-	-	1.2	V	IC=4A, IB=800mA
*VBE(sat)	-	-	1.5	V	IC=4A, IB=800mA
*hFE1	10	-	30		IC=0.5A, VCE=5V
*hFE2	6	-	-		IC=4A, VCE=5V

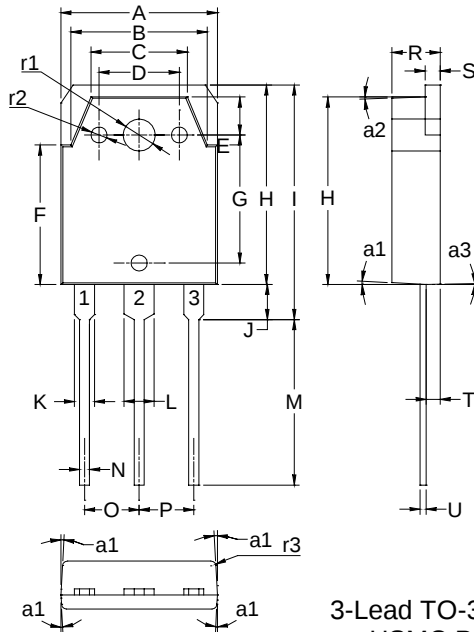
*Pulse Test: Pulse Width ≤380us, Duty Cycle≤2%



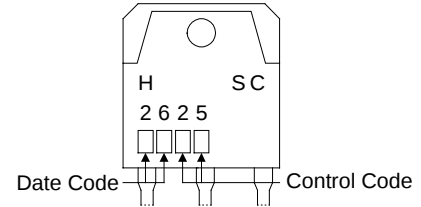
TO-3P



TO-3P Dimension



Marking:



Style: Pin 1.Base 2.Collector 3.Emitter

3-Lead TO-3P Plastic Package,
HSMC Package Code: R

*: Typical

DIM	Inches		Millimeters		DIM	Inches		Millimeters	
	Min.	Max.	Min.	Max.		Min.	Max.	Min.	Max.
A	0.6063	0.6220	15.40	15.80	N	0.0315	0.0472	0.80	1.20
B	0.5276	0.5433	13.40	13.80	O	0.2028	0.2264	5.15	5.75
C	0.3701	0.3858	9.40	9.80	P	0.2028	0.2264	5.15	5.75
D	-	*0.3150	-	*8.00	Q	0.7283	0.7441	18.50	18.90
E	0.1417	0.1575	3.60	4.00	R	0.1811	0.1969	4.60	5.00
F	0.5394	0.5551	13.70	14.10	S	0.0571	0.0650	1.45	1.65
G	0.4945	0.5102	12.56	12.96	T	0.0472	0.0630	1.20	1.60
H	0.7756	0.7913	19.70	20.10	a1	-	*3°	-	*3°
I	0.9134	0.9291	23.20	23.60	a2	-	*2°	-	*2°
J	0.1299	0.1457	3.30	3.70	a3	-	*1°	-	*1°
K	0.0709	0.0866	1.80	2.20	r1	φ3.10	φ3.30	φ3.10	φ3.30
L	0.1102	0.1260	2.80	3.20	r2	-	*φ1.60	-	*φ1.60
M	0.6378	0.6614	16.20	16.80	r3	-	*R0.50	-	*R0.50

Notes: 1.Dimension and tolerance based on our Spec. dated Apr. 25,1996.
2.Controlling dimension: millimeters.
3.Maximum lead thickness includes lead finish thickness, and minimum lead thickness is the minimum thickness of base material.
4.If there is any question with packing specification or packing method, please contact your local HSMC sales office.

Material:

- Lead: 42 Alloy; solder plating
- Mold Compound: Epoxy resin family, flammability solid burning class: UL94V-0

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